

Patent claims:

1. A method for suppressing mold formation on building parts using hydrophobic substances,
5 characterized in that a dispersion of hydrophobic particles having a mean particle diameter of from 0.005 to 5 μ m in an organic dispersant is applied to the surface to be protected from mold attack and the dispersant is then removed.
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2. The method as claimed in claim 1, characterized in that a dispersion containing from 0.1 to 10% by weight, based on the dispersant, of hydrophobic particles is used.
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3. The method as claimed in at least one of claims 1 and 2, characterized in that the hydrophobic particles used are those which comprise a material selected from silica, alumina, titanium oxide,
20 zirconium oxide, polytetrafluoroethylene homopolymer, polytetrafluoroethylene copolymers or mixtures thereof.
4. The method as claimed in at least one of claims 1 to 3, characterized in that a dispersion which comprises ethanol and/or isopropanol as the dispersant is used.
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5. The method as claimed in at least one of claims 1 to 4, characterized in that the application of the dispersion is effected by spraying on.
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6. A composition for building parts which inhibits mold growth, characterized in that it comprises
35 from 0.1 to 10% by weight of hydrophobic particles having a mean particle diameter of from 0.005 to 5 μ m dispersed in an organic dispersant.
7. The composition which inhibits mold growth as

claimed in claim 6, characterized in that it comprises an alcohol as the organic dispersant.